100% Material Declaration Data Sheet QFG48

PK212 (v1.0) October 5, 2006 — Material Declaration Data Sheet

Average Weight: 0.099 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.003168**	**3.20%**
	Silicon	7440-21-3	100.00		0.003168	
Die Attach Material					**0.0008019**	**0.81%**
	Epoxy (EP)	Trade Secret	23.00		0.000184437	
	Silver	7440-22-4	77.00		0.000617463	
Mold Compound					**0.0383328**	**38.72%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.003449952	
	Phenolic Resin	Trade Secret	7.00		0.002683296	
	Carbon Black	1333-86-4	0.50		0.000191664	
	Silica	60676-86-0	82.50		0.03162456	
	Bismuth	7440-69-9	1.00 max		0.000383328	
Leadframe					**0.0543411**	**54.89%**
	Copper	7440-50-8	97.50		0.0529825725	
	Iron	7439-89-6	2.35		0.00127701585	
	Phosphorus	7723-14-0	0.03		0.00001630233	
	Zinc	7440-66-6	0.12		0.00006520932	
Leadframe Plating					**0.0011286**	**1.14%**
	Silver	7440-22-4	100.00		0.0011286	
Bond Wire					**0.0008613**	**0.87%**
	Gold	7440-57-5	100.00		0.0008613	
Ext. Plating					**0.0003663**	**0.37%**
	Tin	7440-31-5	100.00		0.0003663	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.

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